

I) IC Lab Schedule (2009 June PRISM)

DATE	LAB	DESCRIPTION
June 09 (Tuesday_	1	Lab tour; Safety discussion; Determining charge carrier type; Determining resistivity.
June 10	2	Wafer clean; Wet oxidation.
June 11	3	Photolithography Level 1; Oxide etch; Strip resist; Wafer clean; Spin on dopant glass.
June 12	4	Diffuse; Etch dopant glass; Demonstrate diode electrical characteristics.
June 15	5	Photolithography Level 2; Oxide etch; Strip resist; Wafer clean; Gate oxidation
June 16	6	Photolithography Level 3; Oxide etch; Strip resist; Photolithography Level 4.
June 17	7	Evaporate aluminum; Lift-off; Sinter & Anneal; Solder to glass slide
June 18	8	Measurement Experiments 1-6.
June 19	9	Measurement Experiments 1-6.
June 22	10	Measurement Experiments 1-6.
June 23	11	Measurement Experiments 1-6.
June 24	12	Measurement Experiments 1-6.